



WEBINAR ANNOUNCEMENT

Wire-bonding Overview and Packaging Toolsets at Georgia Tech IEN

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Date: June 11, 2020

Time: 11:00 AM – 12:00 PM (EDT)

Abstract: The shared user labs within the Institute for Electronics and Nanotechnology at Georgia Tech include an electronics packaging toolset. A brief overview of assembly and interconnection toolsets and technologies available within IEN will be presented. A process overview on wire-bonding capabilities will also be discussed.

Bio: Mr. Chris White is currently the packaging tool support lead within the Institute for Electronics and Nanotechnology at the Georgia Institute of Technology. He received his bachelor's degree in Electrical Engineering from Georgia Tech in 2009 and started working in the Packaging Research Center on campus to support the research labs within the center. His team currently supports the packaging toolsets within the IEN shared user labs with a primary focus on microelectronics assembly process tools.

Who should attend: Faculty, scientists, engineers, researchers, and technical staff from university, company, or government labs who use, or are interested in learning microelectronics packaging techniques with reference to wire-bong, in particular, as part of their research efforts.

Join the Online Event June 11th at this link: <https://bluejeans.com/291739979>